



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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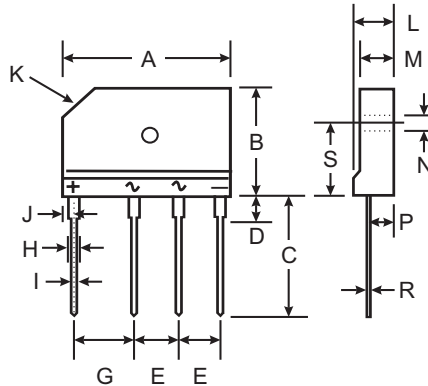


Features

- Glass Passivated Die Construction
- High Case Dielectric Strength of 1500V_{RMS}
- Low Reverse Leakage Current
- Surge Overload Rating to 240A Peak
- Ideal for Printed Circuit Board Applications
- UL Listed Under Recognized Component Index, File Number E94661
- **Lead Free Finish/RoHS Compliant (Note 4)**

Mechanical Data

- Case: GBJ
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Plated Leads, Solderable per MIL-STD-202, Method 208 (E3)
- Lead Free Plating (Tin Finish).
- Polarity: Molded on Body
- Mounting: Through Hole for #6 Screw
- Mounting Torque: 5.0 in-lbs Maximum
- Marking: Type Number
- Weight: 6.6 grams (approximate)



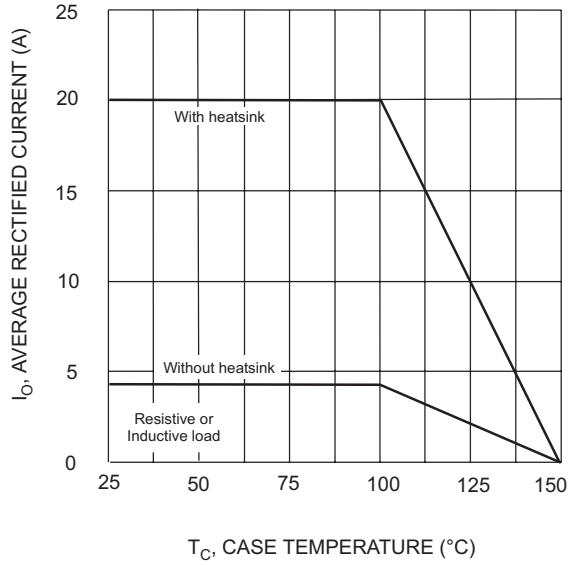
GBJ		
Dim	Min	Max
A	29.70	30.30
B	19.70	20.30
C	17.00	18.00
D	3.80	4.20
E	7.30	7.70
G	9.80	10.20
H	2.00	2.40
I	0.90	1.10
J	2.30	2.70
K	3.0 X 45°	
L	4.40	4.80
M	3.40	3.80
N	3.10	3.40
P	2.50	2.90
R	0.60	0.80
S	10.80	11.20
All Dimensions in mm		

Maximum Ratings and Electrical Characteristics @ T_A = 25°C unless otherwise specified

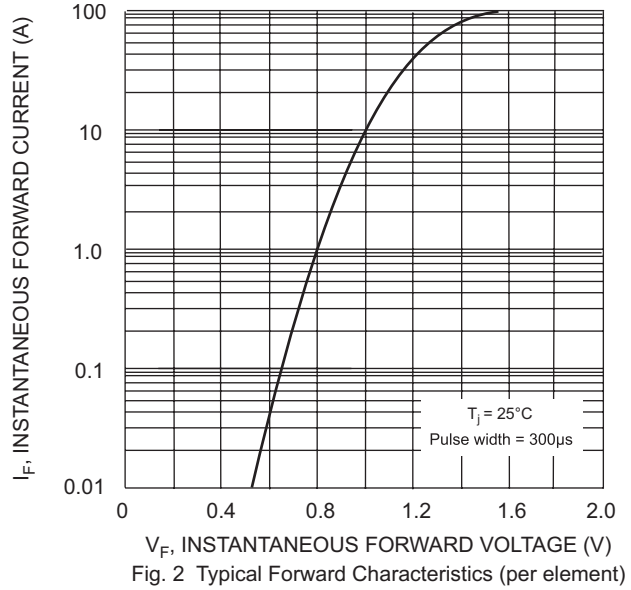
Single phase, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	GBJ 20005	GBJ 2001	GBJ 2002	GBJ 2004	GBJ 2006	GBJ 2008	GBJ 2010	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	280	420	560	700	V
Average Forward Rectified Output Current @ T _C = 110°C	I _O	20							A
Non-Repetitive Peak Forward Surge Current, 8.3 ms single half-sine-wave superimposed on rated load	I _{FSM}	240							A
Forward Voltage per element @ I _F = 10A	V _{FM}	1.05							V
Peak Reverse Current @ T _A = 25°C at Rated DC Blocking Voltage @ T _C = 125°C	I _R	10 500							μA
I ² t Rating for Fusing (t < 8.3 ms) (Note 1)	I ² t	240							A ² s
Typical Total Capacitance per Element (Note 2)	C _T	60							pF
Typical Thermal Resistance Junction to Case (Note 3)	R _{θJC}	0.8							°C/W
Operating and Storage Temperature Range	T _j , T _{STG}	-55 to +150							°C

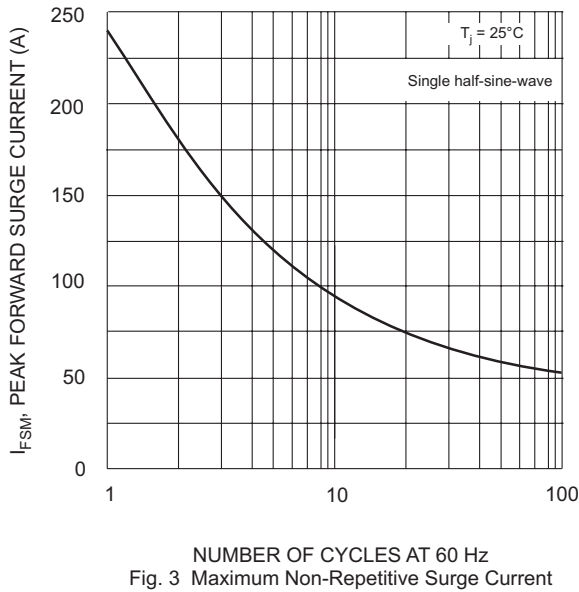
- Notes:
1. Non-repetitive, for t > 1ms and < 8.3 ms.
 2. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.
 3. Unit mounted on 300 x 300 x 1.6mm Cu plate heat sink.
 4. RoHS revision 13.2.2003. Glass and High Temperature Solder Exemptions Applied, see *EU Directive Annex Notes 5 and 7*.



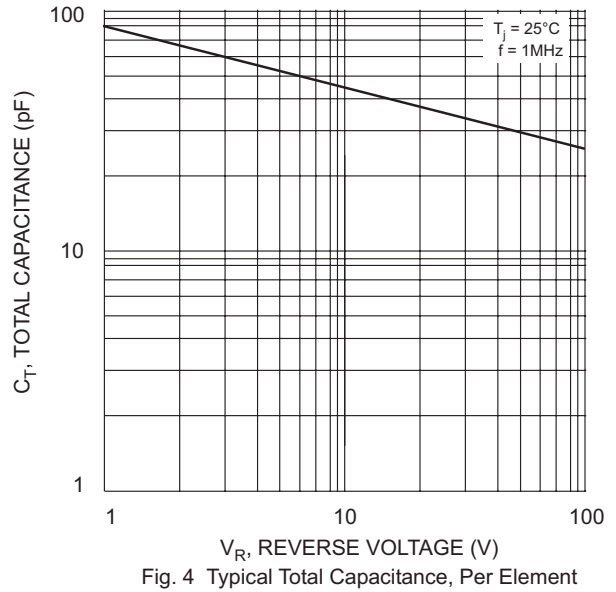
T_C , CASE TEMPERATURE ($^{\circ}C$)
Fig. 1 Forward Current Derating Curve



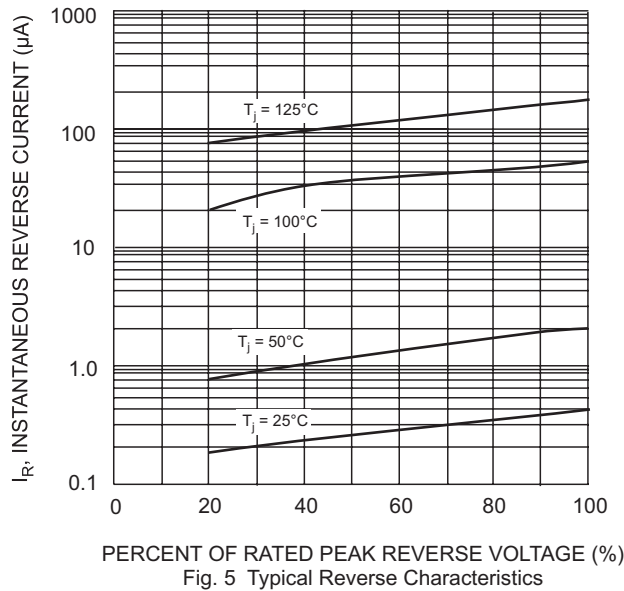
V_F , INSTANTANEOUS FORWARD VOLTAGE (V)
Fig. 2 Typical Forward Characteristics (per element)



NUMBER OF CYCLES AT 60 Hz
Fig. 3 Maximum Non-Repetitive Surge Current



V_R , REVERSE VOLTAGE (V)
Fig. 4 Typical Total Capacitance, Per Element



PERCENT OF RATED PEAK REVERSE VOLTAGE (%)
Fig. 5 Typical Reverse Characteristics

Ordering Information (Note 5)

Device	Packaging	Shipping
GBJ20005-F	GBJ	15/Tube
GBJ2001-F	GBJ	15/Tube
GBJ2002-F	GBJ	15/Tube
GBJ2004-F	GBJ	15/Tube
GBJ2006-F	GBJ	15/Tube
GBJ2008-F	GBJ	15/Tube
GBJ2010-F	GBJ	15/Tube

Notes: 5. For packaging details, visit our website at <http://www.diodes.com/datasheets/ap2008.pdf>.

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